



Research on Building Wall Insulation Materials

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Message from the Guest Editor

Due to the general need to reach the sustainable development goals, this Special Issue will promote the development of sustainable products (i.e., wood-based boards for wall panels, recycled materials, environmental friendly materials) and the application of the latest technology via the adoption of building information modeling (BIM)[...]

For further reading, please follow the link to the Special Issue Website at:
[https://www.mdpi.com/journal/buildings/special_issues/
Building_Insulation](https://www.mdpi.com/journal/buildings/special_issues/Building_Insulation)





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Message from the Editor-in-Chief

Current urban environments are home to multi-modal transit systems, extensive energy grids, a building stock, and integrated services. Sprawling neighborhoods are composed of buildings that accommodate living and working quarters. However, it is expected that the cities and communities of the future will face complex and enormous challenges, including maintenance, interconnectivity, resilience, energy efficiency, and sustainability issues, to name but a few. A smart city uses advanced technologies and a digital infrastructure to improve the outcomes in every aspect of a city's operations. A smart building optimizes the experience of occupants, staff, and management by using a modern and connected environment. Innovations in technology that can bring dramatic improvements to design, planning, and policy are critical in developing the cities and buildings of the future.

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